



## Material Content Data Sheet



Sales Product Name	IPD60R2K0PFD7S			Issued		25. November 2019		
MA#	MA004221022							
Package	PG-TO252-3-344			Weight*		321.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.842	0.26	0.26	2619	2619
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		134	
	non noble metal	iron	7439-89-6	0.144	0.04		448	
	non noble metal	copper	7440-50-8	143.904	44.79	44.84	447742	448324
wire	non noble metal	aluminium	7429-90-5	0.150	0.05	0.05	466	466
encapsulation	organic material	carbon black	1333-86-4	0.691	0.21		2149	
	plastics	epoxy resin	-	18.652	5.80		58035	
	inorganic material	silicondioxide	60676-86-0	118.823	36.97	42.98	369705	429889
leadfinish	non noble metal	tin	7440-31-5	3.834	1.19	1.19	11928	11928
solder	non noble metal	tin	7440-31-5	0.026	0.01		80	
	noble metal	silver	7440-22-4	0.032	0.01		100	
	non noble metal	lead	7439-92-1	1.222	0.38	0.40	3801	3981
heatspreader	inorganic material	phosphorus	7723-14-0	0.010	0.00		31	
	non noble metal	iron	7439-89-6	0.033	0.01		103	
	non noble metal	copper	7440-50-8	32.995	10.27	10.28	102659	102793
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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